

SOT-23 Plastic-Encapsulate MOSFETS

20V N-Channel Enhancement Mode MOSFET

VDS= 20V

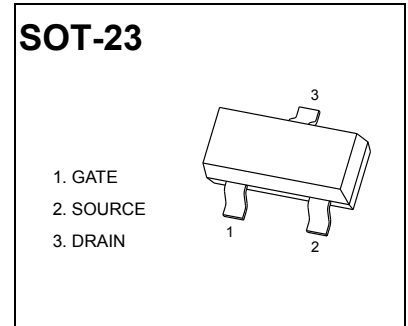
RDS(ON), Vgs@ 4.5V, Ids@ 2.0A < 50mΩ

RDS(ON), Vgs@ 2.5V, Ids@ 1.0A < 80mΩ

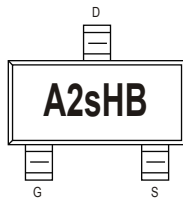
Features

Advanced trench process technology

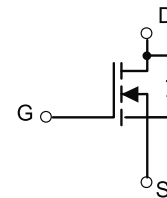
High Density Cell Design For Ultra Low On-Resistance



MARKING



Equivalent circuit



PACKAGE SPECIFICATIONS

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (pcs)	Box Size (mm)	QTY/Box (pcs)	Carton Size (mm)	Q'TY/Carton (pcs)
SOT-23	7'	330	3000	203×203×195	45000	438×438×220	180000

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±12	
Continuous Drain Current	I _D	2.3	A
Pulsed Drain Current ¹⁾	I _{DM}	6	
Maximum Power Dissipation ²⁾	P _D	0.6	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C

Notes

¹⁾ Pulse width limited by maximum junction temperature.

²⁾ Surface Mounted on FR4 Board, t ≤ 5 sec.

The above data are for reference only.



MOSFET ELECTRICAL CHARACTERISTICS

T_a = 25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D = 250uA	20			V
Drain-Source On-State Resistance ¹⁾	R _{DS(on)}	V _{GS} = 4.5V, I _D = 2.0A			50	mΩ
		V _{GS} = 2.5V, I _D = 1.0A			80	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.6		1.1	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 19.5V, V _{GS} = 0V			1	uA
Gate Body Leakage	I _{GSS}	V _{GS} = 12V, V _{DS} = 0V			100	nA
Forward Transconductance ¹⁾	g _{fs}	V _{DS} = 5V, I _D = 2.3A		10	—	S
Dynamic						
Total Gate Charge	Q _g	V _{DS} = 10V, I _D = 2.3A V _{GS} = 4.5V		5.4		nC
Gate-Source Charge	Q _{gs}			0.65		
Gate-Drain Charge	Q _{gd}			1.6		
Turn-On Delay Time	t _{d(on)}	V _{DD} = 10V, R _L = 5.5Ω I _D = 2.3A, V _{GEN} = 4.5V R _G = 6Ω		12		ns
Turn-On Rise Time	t _r			36		
Turn-Off Delay Time	t _{d(off)}			34		
Turn-Off Fall Time	t _f			10		
Input Capacitance	C _{iss}	V _{DS} = 10V, V _{GS} = 0V f = 1.0 MHz		340		pF
Output Capacitance	C _{oss}			115		
Reverse Transfer Capacitance	C _{rss}			33		
Diode Forward Voltage	V _{SD}	I _S = 1.0A, V _{GS} = 0V			1.2	V

¹⁾ Pulse test: pulse width <= 300us, duty cycle <= 2%

Typical Electrical and Thermal Characteristics

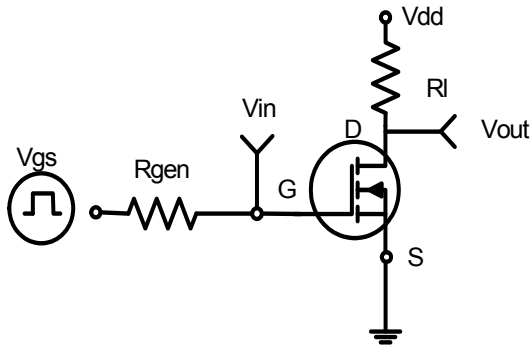


Figure 1: Switching Test Circuit

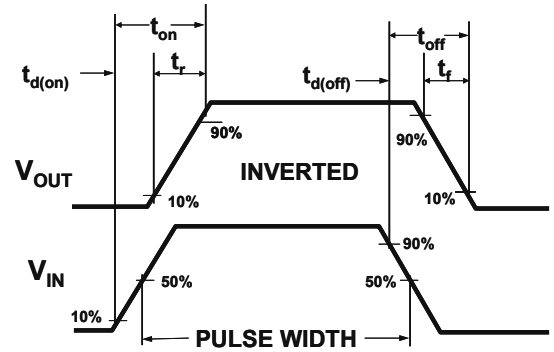


Figure 2: Switching Waveforms

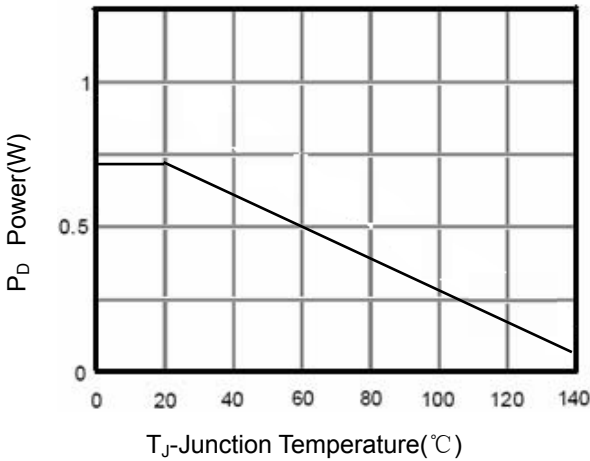


Figure 3 Power Dissipation

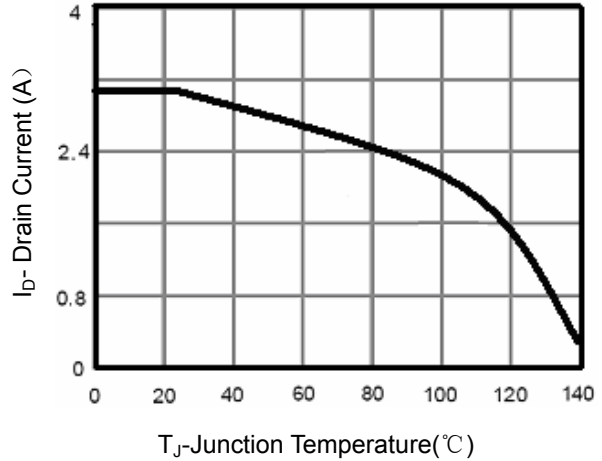


Figure 4 Drain Current

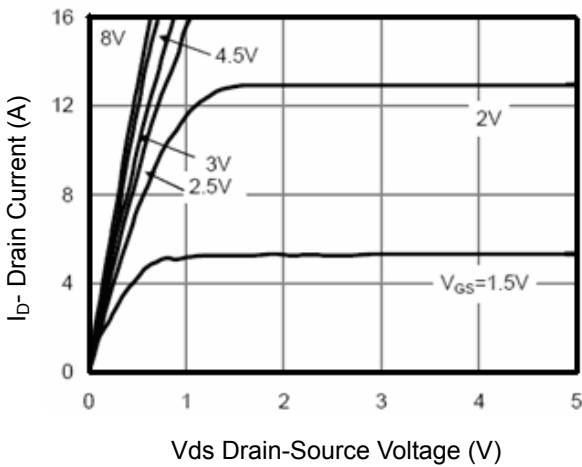


Figure 5 Output Characteristics

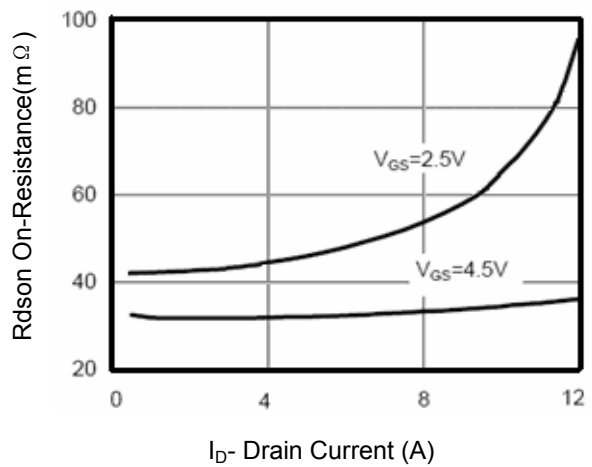


Figure 6 Drain-Source On-Resistance

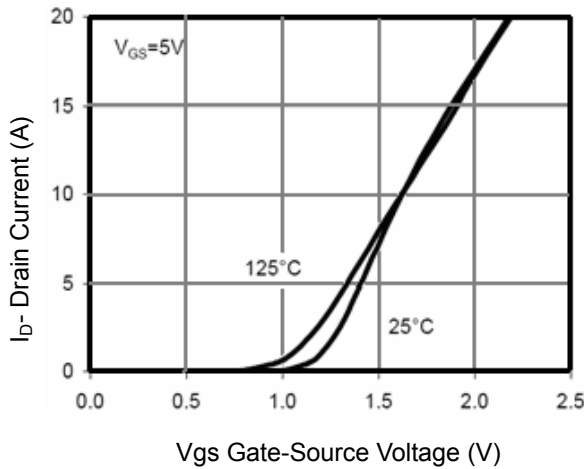


Figure 7 Transfer Characteristics

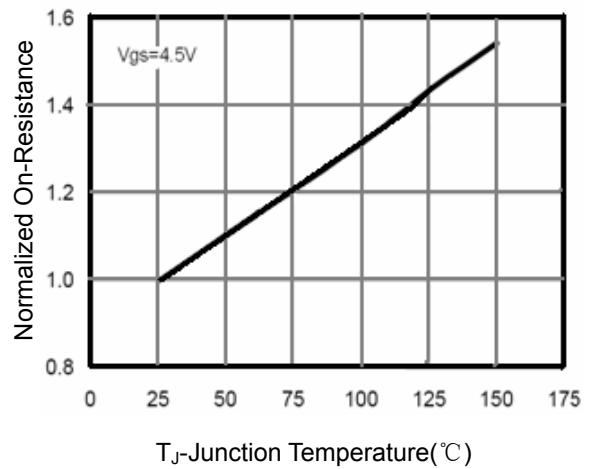


Figure 8 Drain-Source On-Resistance

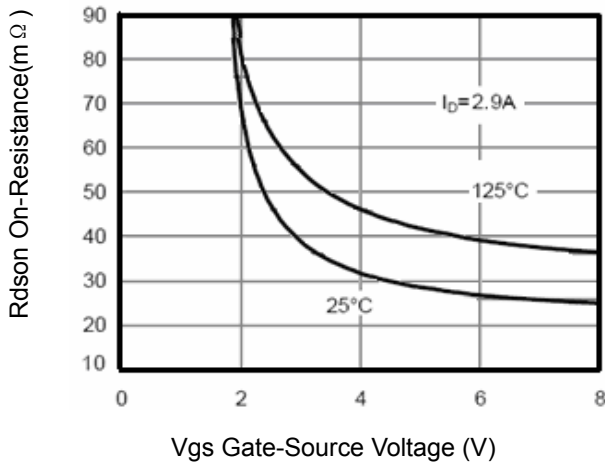


Figure 9 Rdson vs Vgs

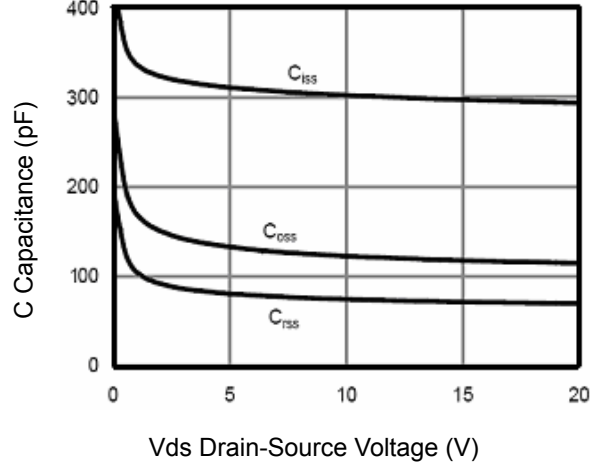


Figure 10 Capacitance vs Vds

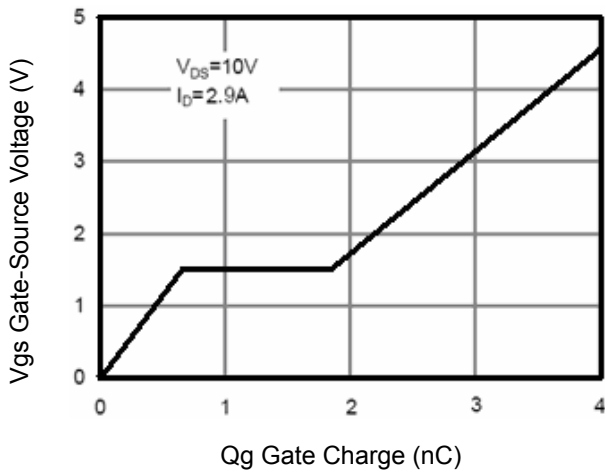


Figure 11 Gate Charge

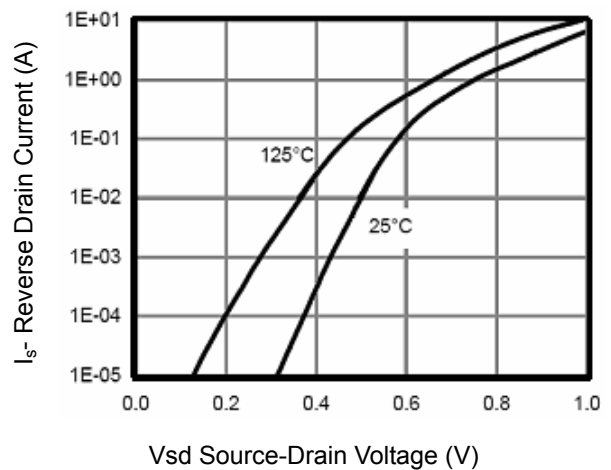


Figure 12 Source- Drain Diode Forward

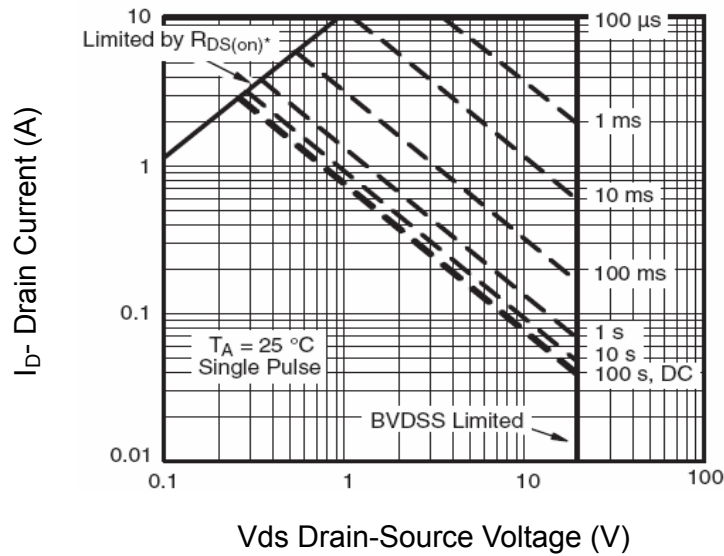


Figure 13 Safe Operation Area

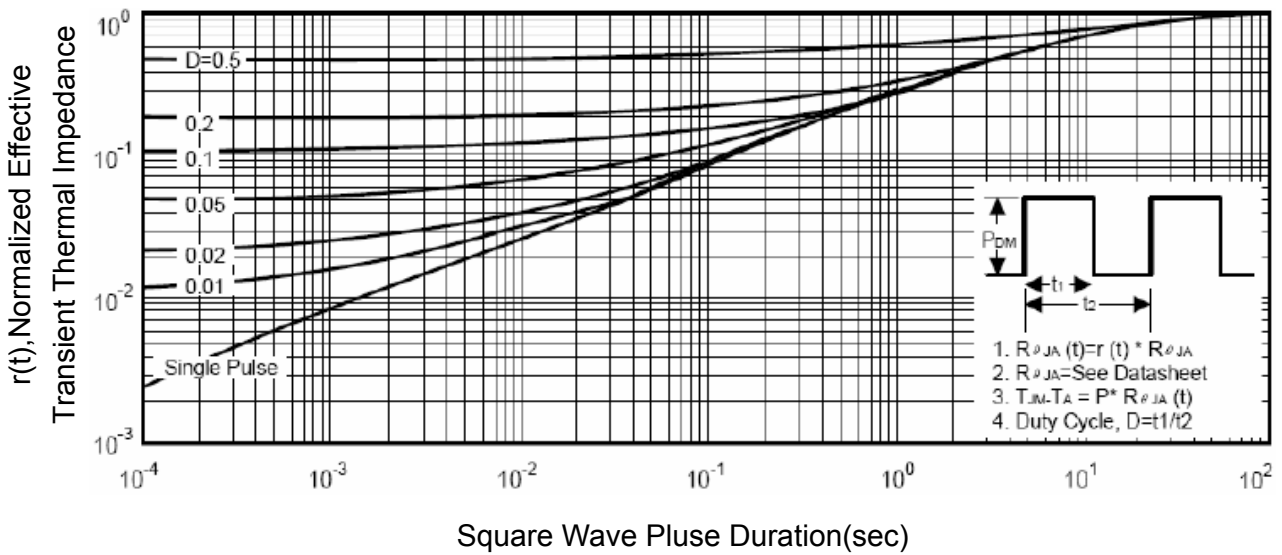
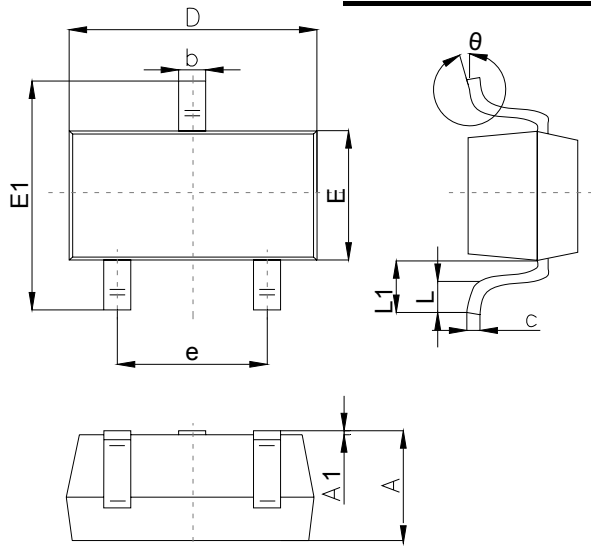


Figure 14 Normalized Maximum Transient Thermal Impedance

The curve above is for reference only.

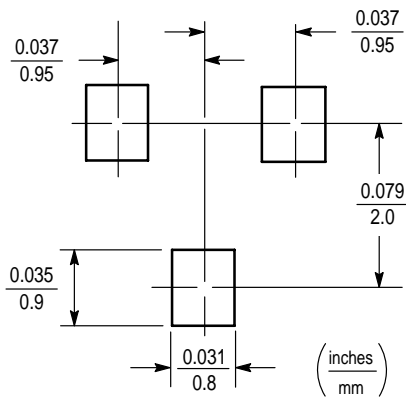
Outlitne Drawing

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		
	Min	Typ	Max
A	0.90		1.40
A1	0.00		0.10
b	0.30		0.50
c	0.08		0.20
D	2.80	2.90	3.10
E	1.20		1.60
E1	2.25		2.80
e	1.80	1.90	2.00
L	0.10		0.50
L1	0.4		0.55
θ	0°		10°

Suggested Pad Layout



Note:

1. Controlling dimension: in/millimeters.
2. General tolerance: ±0.05mm.
3. The pad layout is for reference purposes only.